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Name: KUBOVCIK & KUBOVCIK
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Washington, D.C. 20006

7. Total number of applications and patents involved:

1

8. Total fee (37 CFR 3.41) \$ 40.00

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11. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Keiko Tanaka Kubovcik
Name of Person Signing


Signature

January 9, 2006
Date

40,428
Registration Number

Total number of pages, including cover sheet, attachments, and document:

3

Atty. Docket No. ABE-034

KTK/jbf

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

(Insert ASSIGNEE'S
Name(s) Address(es))

Sumco Corporation
2-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8634, Japan

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of Invention)

Bonded semiconductor substrate and manufacturing method thereof

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

(*If the assignment is
being filed after the
filing of the
application, this section
must be completed)

*filed on _____, Serial No. 10/550,761
(Kubovcik & Kubovcik is hereby authorized to insert the series code, serial number and/or filing date, when known)

and to all Letters Patent of the United States to be obtained thereof on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with this application and any continuing, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(signatures)

<u>Eiji Kamiyama</u> (SIGNATURE)	<u>Eiji Kamiyama</u> (TYPE NAME)	<u>16/9/2005</u> (DATE)
<u>Takeo Katoh</u> (SIGNATURE)	<u>Takeo Katoh</u> (TYPE NAME)	<u>20/9/2005</u> (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)

NO LEGALIZATION REQUIRED

08/00